

## **Amendments to the Claims**

1-20. (withdrawn)

21. (currently amended) A method of co-depositing multicrystalline particles comprising the steps of:

suspending the multicrystalline particles in a suspension;

applying at least one magnetic field to the particles in order to vary a co-deposition rate or location of the particles;

co-depositing the particles along with at least one component of the suspension;

and

forming a desired structure.

22. (original) The method of claim 21 wherein the applying step comprises controlling at least one deposition location of the particles.

23. (original) The method of claim 21 wherein the applying step comprises controlling a particle loading.

24. (original) The method of claim 21 wherein the particles are magnetic.

25. (original) The method of claim 22 wherein the particles have been coated with at least one coating.

26. (original) The method of claim 25 wherein the coating is magnetic.

27. (original) The method of claim 21 wherein the suspending step comprises suspending the particles in an electrolytic solution.

28. (original) The method of claim 27 wherein the co-depositing step comprises co-depositing in one deposition step at least two materials with incompatible electropotentials.

29. (original) The method of claim 21 wherein the suspending step comprises suspending the particles in an ink or paste.

30. (original) The method of claim 22 wherein the forming step comprises filling a via.

31. (original) The method of claim 30 wherein the forming step comprises accelerating a fill rate by controlling particle loading.

32. (original) The method of claim 30 wherein the forming step further comprises controlling the particle location with at least one external magnetic field, thereby permitting fill electrodeposition within the via without the presence of prior seed metallization of an entire surface of the via.

33. (original) A method of making a via comprising the steps of:  
providing seed metallization to only a portion of a surface of the via;  
filling the via with a material comprising conducting particles.

34-37. (withdrawn)